Asahi KASEI MICRODEVICES

AP2152

3CH High Power WLED Driver

DESCRIPTION

The AP2152 is a 3 channel white LED driver IC. It is composed of a current mode DC/DC boost converter with an internal power MOSFET and 3 channel constant current sources, which can drive up to 10 LEDs per channel for a maximum of 30 LEDs.

The AP2152 achieves ±0.8% typ. LED current matching between each channel when the LED current is set at 75.8mA. The LED current can be run up to a maximum of 120mA with the appropriate external set resistor on the ISET pin.

The AP2152 operates over a wide input voltage range from 4.25V to 35V, and the switching frequency goes up to a maximum of 2.5MHz with the appropriate external set resistor on the RT pin. The switching frequency can also be synchronized with an external signal.

The AP2152 provides the LED dimming function via an external PWM signal, with a frequency range from 100Hz to 20KHz.

The AP2152 provides LED open protection, LED short protection, OVP pin short protection, channel short protection, over voltage protection, over current protection, thermal protection and UVLO.

FEATURES

- White LED driving number: Maximum 30 pieces (10 pieces in series x 3 in parallel)
- LED current matching: ±0.8% typ. (I_{LED}=75.8mA)
- LED maximum current: 120mA
- Maximum switching frequency: 2.5MHz
- PWM dimming frequency by applying external signal: Maximum 20kHz
- Input voltage range: 4.25V~35V
- Built-in 45V power MOSFET
- Error flag through serial interface
- **Synchronize with External frequency**
- Master Slave configuration
- LED open protection
- LED short protection
- OVP pin short protection
- Output channel short protection
- Overvoltage protection (OVP)
- Over current protection
- Thermal protection
- UVLO
- 20 pin HTSSOP with heat-sink package

APPLICATIONS

- Display backlight
- Lighting equipment

BLOCK DIAGRAM

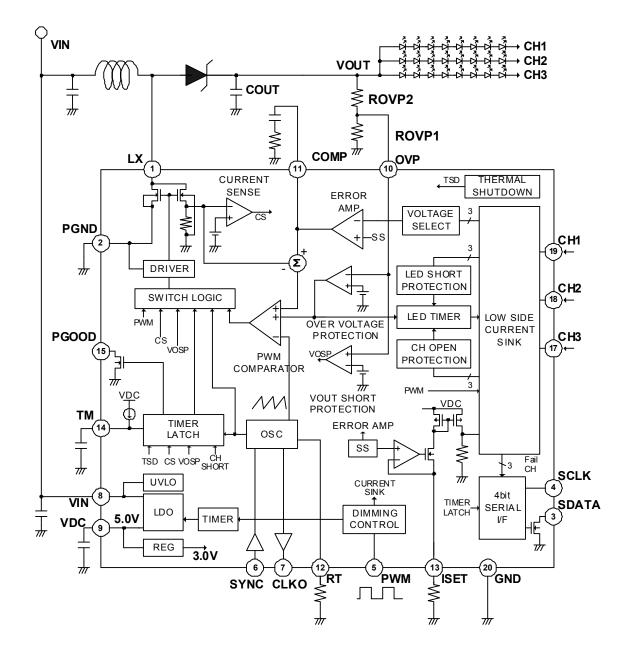
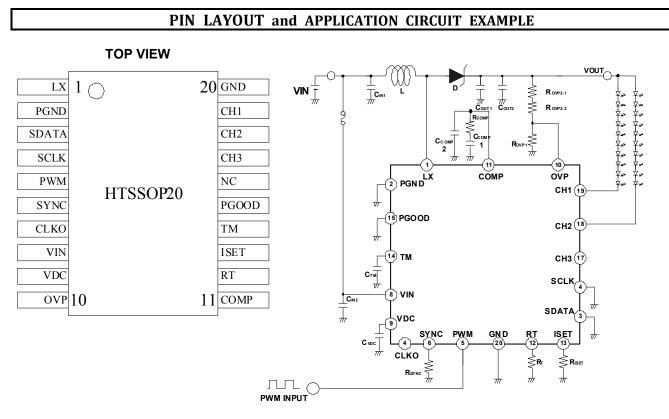
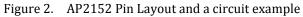


Figure 1. AP2152 Block Diagram





PIN DESCRIPTION

| Pin No. | Pin Name | Function |
|---------|----------|--|
| 1 | LX | Power MOSFET pin. Nch MOSFET open-drain. If 2.6A or higher current is detected on this pin, over-current protection circuit is activated. |
| 2 | PGND | GND for power MOSFET |
| 3 | SDATA | Data output from serial interface. Nch open-drain output. The output data will be synchronized with the clock input on the SCLK pin When the data function is unnecessary please connect to GND. |
| 4 | SCLK | Clock input for serial interface. When the clock function is unnecessary please connect to GND. |
| 5 | PWM | PWM dimming signal input pin. Built-in $200k\Omega$ pull down resistor. This also functions as the enable input, and if this pin goes to a high level, the IC is changed from the stand-by state to the enable state, the internal LDO is activated, and the boost operation begins. If this pin goes to a low level, the internal timer starts counting, 30msec later the IC goes into the standby state. |
| 6 | SYNC | Clock input pin for synchronous operation. Built-in $1M\Omega$ pull-down resistor. If the synchronous operation is unnecessary, please connect to GND. |
| 7 | CLKO | Internal clock output pin. If the clock function is unnecessary, please keep this pin open. |
| 8 | VIN | Power input pin. Internal LDO input to provide power for internal circuits. 1.0µF should be connected between the VIN pin and GND. |
| 9 | VDC | Internal LDO output pin. 5V output by regulating from VIN. Maximum output current is 30 mA. 1.0μ F should be connected between the VDC pin and GND. |
| 10 | OVP | Over voltage protection detection circuit input pin. The voltage at the OVP pin is the LED Anode voltage divided by the resistor divider. If the voltage exceeds 1.2V, the boosted LED anode voltage will be suppressed. If the voltage goes below 0.1V, the OVP pin short protection circuit is activated. |
| 11 | СОМР | DC/DC boost converter phase compensation pin. A resistor and a capacitor should be connected between the COMP pin and GND. |

| Pin No. | Pin Name | Function |
|---------|----------------|---|
| 12 | RT | Switching frequency set pin. Oscillation frequency can be set by connecting a resistor between the RT pin and GND. Please refer to section 2.4 "Switching frequency |
| | | setting/Function of synchronizing with external clock". |
| 13 | ISET | LED driving current set pin. LED current can be set by connecting a resistor between the |
| | | ISET pin and GND. Please refer to section 2.3 "LED current setting". |
| 14 | ТМ | Capacitor connection pin for timer. If an abnormality occurs in the IC, this pin outputs 10μ A constant current. If this pin voltage exceeds 2.0V, the IC ceases its operation. By returning to the standby state, the timer is reset and the IC can be released. When the timer is unnecessary, please connect to GND. Please refer to section 2.6 "Timer latch (TM) setting". |
| 15 | PGOOD | Power Good pin. N channel open-drain, it keeps OFF when normal operation. If an abnormality occurs in the IC, the operation is latched off by timer latch function and internal FET turns ON. Please refer to "Protections description" for the detail of Power Good pin status described later. When the power good function is unnecessary, please connect to GND. |
| 16 | NC | NC pin. |
| 17 | СН3 | WLEDs constant current circuit 3. CH3 is open drain, and provides constant current to the LEDs. If this constant current channel is unnecessary, please keep this pin open. |
| 18 | CH2 | WLEDs constant current circuit 2. CH2 is open drain, and provides constant current to LEDs. If this constant current channel is unnecessary, please keep this pin open. |
| 19 | CH1 | WLEDs constant current circuit 1. CH1 is open drain, and provides constant current to LEDs. If this constant current channel is unnecessary, please keep this pin open. |
| 20 | GND | GND pin for internal circuits. |
| - | THERMAL PAD | For heat radiation, connection to GND is recommended. This is electrically isolated from the internal circuit. |

ABSOLUTE MAXIMUM RATINGS

| Rating | Symbol | Value | Unit | Condition |
|--|--------------------------------------|---------------------------------|------|-----------|
| VIN voltage | V _{IN} | -0.3 to +45 | V | *1 |
| LX, CH1-3 Voltage | V _{LX} , V _{CH} | -0.3 to +45 | v | *1 |
| SDATA, SCLK, PWM,VDC, PGOOD, SYNC voltage | - | -0.3 to +6 | v | *1 |
| OVP, COMP, RT, ISET, TM, CLKO voltage | - | -0.3 to (V _{DC} + 0.3) | V | *1*4 |
| CH1-3 current | I _{CH} | 140 | mA | |
| PGOOD current | I _{GOOD} | 20 | mA | |
| Power Dissipation | PD | 2500 | mW | *2, *3 |
| Operating Temperature Range | T _{OP} | -40 ~ +105 | °C | |
| Storage Temperature Range | T _{STG} | -55 ~ +150 | °C | |

Note:

*1. All voltages refer to GND pin (GND, PGND) as zero (reference) voltage.

*2. PD must be decreased at the rate of 23.3mW/°C for operation above 25°C.

*3. Mounted on a 50 mm \times 50 mm x 1 mm double sided FR-4 board.

*4. The maximum value is limited to 6.0V if V_{DC} exceeds 5.7V.

Note: The maximum ratings are the absolute limitation values with the possibility of damage/breakage.

When operation exceeds this standard, quality cannot be guaranteed.

ELECTRICAL CHARACTERISTICS

 V_{IN} =12V, GND=PGND=0V, R_{ISET} =36k Ω , R_{T} =91k Ω , PWM=5V, T_{A} =+25°C unless otherwise specified. Items marked by \bullet are guaranteed by design in the range of -30°C to +85°C.

| D i | Nature Value | | | | a 1111 | | | |
|-------------------------------|-----------------------|---|-------|------|---------------|------|--|--|
| Parameter | Symbol | | MIN | ТҮР | MAX | Unit | Condition | |
| DC/DC Converter | | | | | | | | |
| Input voltage Range | VIN | • | 4.25 | | 35 | V | | |
| Supply Current(SW ON) | I _{DD} | | | 5 | 10 | mA | | |
| Standby Current | I _{STB} | | | 5.0 | 10 | μΑ | After start up PWM =0V *1 | |
| UVLO Voltage | V _{UVLO} | | 3.75 | 4.0 | 4.25 | V | UVLO On V _{IN} | |
| UVLO Hysteresis Width | V _{HYS_UVLO} | | | 0.2 | | V | UVLO Off VIN | |
| | | | 1.86 | 2.0 | 2.14 | MHz | $R_{\rm T}=55k\Omega$ | |
| Switching Frequency | F | • | 1.80 | 2.0 | 2.17 | MHz | $R_{\rm T}$ =55KM | |
| Switching Frequency | Fosc | | 1.21 | 1.3 | 1.39 | MHz | $R_{\rm T}=91k\Omega$ | |
| | | • | 1.18 | 1.3 | 1.42 | MHz | NT-91KM | |
| LX On Resistance | R _{LX} | | | 400 | 800 | mΩ | I _{LX} =+30mA | |
| LX Off Leak Current | I _{LEAK_LX} | | | 0.1 | 1.0 | μΑ | V _{LX} =45V | |
| Maximum On Duty | D _{MAX} | | 90 | 95 | | % | F _{OSC} =1.3MHz | |
| LX Minimum On Time | T _{LX_MIN} | • | | | 50 | ns | | |
| COMP Output High Voltage | V _{OH_COMP} | | 4.55 | 4.9 | | V | I _{COMP} =-10μA | |
| COMP Output Low Voltage | V _{OL_COMP} | | | 0.1 | 0.2 | V | $I_{COMP} = +10 \mu A$ | |
| | V _{REF_EA} | | | 680 | 800 | 920 | mV | |
| Error Amp Reference Voltage | | • | 600 | 800 | 1000 | mV | $R_{ISET}=36 k\Omega$ | |
| Current Sink Circuit and Dimn | ning Part | | | | | | | |
| LED Current Range | ILED | • | 10 | | 120 | mA | | |
| | | | | 75.8 | 78.46 | | $R_{ISET}=36k\Omega$ | |
| | | | 73.15 | | | mA | $I_{\text{LED}}_{\text{TYP}}(\text{mA})$ | |
| | | | | | | | $=\frac{I_{CH(1-3)MAX} + I_{CH(1-3)MIN}}{2}$ | |
| | I_{LED_TYP1} | | | | 79.21 | | $R_{ISET}=36k\Omega$ | |
| | | | | | | | $I_{\text{LED}} \text{TYP} (\text{mA})$ | |
| | | • | 72.39 | 75.8 | | mA | $= \frac{I_{CH}(1-3)MAX + I_{CH}(1-3)MIN}{I_{CH}(1-3)MIN}$ | |
| | | | | | | | $=\frac{\operatorname{CH}(1-5)\operatorname{MAX}}{2}$ | |
| | | | | | | | $R_{ISET}=91k\Omega$ | |
| LED Current | | | 28.8 | 30.0 | 31.2 | mA | $I_{\text{LED}}_{\text{TYP}}(\text{mA})$ | |
| LED Current | | | 20.0 | 30.0 | 51.2 | IIIA | $= \frac{I_{CH}(1-3)MAX + I_{CH}(1-3)MIN}{I_{CH}(1-3)MIN}$ | |
| | I _{LED TYP2} | | | | | | 2 | |
| | ILED_ITP2 | | | | | | $R_{ISET}=91k\Omega$ | |
| | | • | 28.5 | 30.0 | 31.5 | mA | I _{LED TYP} (mA) | |
| | | | | | | | $=\frac{I_{CH(1-3)MAX} + I_{CH(1-3)MIN}}{2}$ | |
| | | | | | | | $R_{ISET}=42k\Omega$ | |
| | | | (0.55 | | (= | | $I_{\text{LED}} \text{TYP}(\text{mA})$ | |
| | I _{LED_TYP3} | • | 62.08 | 65.0 | 67.93 | mA | $\frac{I_{CH(1-3)MAX} + I_{CH(1-3)MIN}}{I_{CH(1-3)MIN}}$ | |
| | | | | | | | $=\frac{1}{2}$ | |

Electrical Characteristics (continuation)

| Davamatar | Symbol | | Value | | | Unit | Condition |
|--|-----------------------|---|--------------|------------|--------------|--------|---|
| Parameter | | | MIN TYP MAX | | Unit | | |
| | ΔI_{LED1} | | -2.5 | ±0.8 | +2.5 | % | $\begin{array}{l} R_{ISET}{=}36k\Omega,\\ ILED_TYP{=}75.8mA\\ \bigtriangleup I_{LED}(\%){=}\\ \frac{I_{CH(1-3)MAX}-I_{CH(1-3)MIN}}{I_{CH(1-3)MAX}+I_{CH(1-3)MIN}} \times 100 \end{array}$ |
| LED Current Accuracy Between Channels | ΔI_{LED2} | | -5.0 | ±1.5 | +5.0 | % | $\begin{array}{l} R_{ISET}{=} 91 k\Omega \text{,} \\ ILED_TYP{=}30.0 mA \\ \bigtriangleup^{I}_{LED} (\%) = \\ \frac{I_{CH(1-3)MAX} - I_{CH(1-3)MIN}}{I_{CH(1-3)MAX} + I_{CH(1-3)MIN}} \times 100 \end{array}$ |
| | ΔI_{LED3} | • | -2.5 | ±0.8 | +2.5 | % | $\begin{array}{l} R_{ISET}{=}\;42k\Omega,\\ ILED_TYP{=}65.0mA\\ \bigtriangleup I_{LED}(\%){=}\\ \frac{I_{CH(1{-}3)MAX}-I_{CH(1{-}3)MIN}}{I_{CH(1{-}3)MAX}+I_{CH(1{-}3)MIN}}{\times}100 \end{array}$ |
| LED Current Delay Time | tr | • | | 1 | 2 | μs | LED Current Rising Time to PWM Input R _T =55kΩ |
| LLD Gurrent Delay Thire | tf | • | | 0.5 | 1 | μο | LED Current Falling Time to PWM Input $R_T=55k\Omega$ |
| LDO | • | | | • | • | | |
| Output Voltage | V _{DC} | • | 4.75 4.50 | 5.0 5.0 | 5.25 5.50 | V V | V _{IN} =12V, I _{DC} =10mA |
| Protection Function | | - | 1100 | 510 | 0.00 | | |
| OVP Reference Voltage | V _{OVP} | • | 1.15 | 1.2 | 1.25 | V | |
| LED Short Criterion Voltage | V _{SHT} | | 10.8 | 12 | 13.2 | V | CH1~CH3 pin |
| LX Limited Current | I _{LX_LIMIT} | | | 2.6 | | А | |
| PGOOD On Resistance | R _{PGOOD} | | | | 100 | Ω | I _{PGOOD} =+10mA |
| TM Voltage | V _{TM} | | 1.9 | 2.0 | 2.1 | V | |
| TM Constant Output Current | I _{TM} | | 8 | 10 | 12 | μA | TM=1.0V |
| Switching Frequency Range | Fosc | • | 0.2 | | 2.5 | MHz | |
| Input High Level Voltage | VIH | ٠ | 2.1 | | | V | PWM, SCLK, SYNC |
| Input Low Level Voltage | VIL | • | | | 0.7 | V | PWM, SCLK, SYNC |
| CLKO Output High Level Voltage | V _{OH_CLKO} | | 4.0 | | | V | I _{CLKO} =-1mA |
| CLKO Output Low Level Voltage | $V_{\text{OL_CLKO}}$ | | | | 0.3 | V | I _{CLKO} =+1mA |

*1.

Normally, when 4.25V is applied to VIN for shorter than $100\mu s$, while the PWM pin is kept at a low level, the IC will be in the standby mode.

However, if 4.25V is applied to VIN for longer than $300\mu s$, the current consumption of the IC is about $900\mu A$. In order to get the IC into standby mode, after inputting a H level to the PWM pin for more than $36\mu s$, a L level needs to be maintained for more than 50m s.

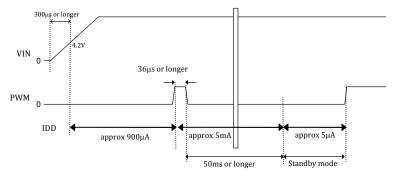
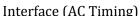


Figure 3. Power Supply Rising Time and Standby mode

| Davamator | Crumph al | Symbol | | Value | | | Condition |
|----------------------------|-----------------------|--------|------|-------|-----|------|---|
| Parameter | Symbol | | MIN | ТҮР | MAX | Unit | Condition |
| PWM | | | | | | | |
| PWM Minimum High | т | | | 15 | 30 | μs | Before Startup |
| Time 1 | T_{PWM_MIN1} | • | | 15 | 36 | μs | Before Startup |
| PWM Minimum High Time 2 | T _{PWM_MIN2} | • | | 5 | 7 | μs | After Startup |
| Shutdown Time | T _{SD} | • | 20 | 30 | 50 | ms | |
| PWM Dimming Frequency | F _{PWM} | | 0.1 | | 20 | kHz | F _{PWM} ≤F _{osc} / 65 |
| Range | I PWM | | 0.1 | | 20 | KIIZ | PPWM≤P0sc / 03 |
| SYNC | | | | | | | |
| SYNC Input Frequency | F _{SYNC} | • | 0.21 | | 2.5 | MHz | |
| Range | ISYNC | Ū | 0.21 | | 2.5 | MIIZ | |
| SYNC Input Duty | D _{SYNC} | • | 20 | | 80 | % | |
| Serial Timing | | | | | | | |
| SCLK Cycle | t _{SCKP} | | 10 | | | μs | |
| SCLK Pulse Width | tsckw | | 5 | | | μs | |
| SDATA Delay | t sdtw | | 3 | | | μs | |



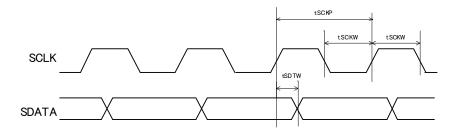


Figure 4. Serial Interface Wave Form

OPERATION

1) Operation Outline

The AP2152 is composed of a current mode DC/DC boost convertor, 3 LED constant current source channels, an LDO, and several protection circuits. It can drive a single LED line to three LED lines connected together with a common anode. (Any unused channel should be left open) This current mode DC/DC boost convertor has a built-in a power MOSFET, and the switching frequency is determined by an external resistor or an external clock signal. The LED anode voltage is optimized by monitoring each channel's voltage and the channel voltage that has the highest forward voltage is chosen. This voltage is used to control the DC/DC boost convertor's output voltage . constant current circuits for driving the LEDs are set by an external resistor, and PWM dimming is possible by applying a PWM signal to the PWM pin. The latch-off time for the protection circuits, such over current protection, channel short protection, and thermal protection can be set. There is also a PGOOD pin to output the latch-off status.

The AP2152 flowchart at startup is shown in Figure 5.

When all CH pins are used, applying a PWM signal begins the DC/DC boost convertor operation. The LED anode voltage rises, and if the LED current of all the CH reaches 1/10 of the set current, the soft-start circuit is activated and the LED current gradually increases in approximately 1ms, and LEDs are lit.

If there are any unused CH pins, the LED open detection circuit is activated at the beginning of the DC/DC boost converter operation as soon as the PWM signal is applied. When the LED anode voltage reaches the OVP preset value, the OVP state is detected. If a CH pin has not reached 1/10 of the LED set current, an open state is recognized, and the LED constant current circuit will cease. For CH pins connected to LEDs, the LED current reaches 1/10 of the set current, the normal connection is recognized, and the LEDs are lit after the soft-start operation.

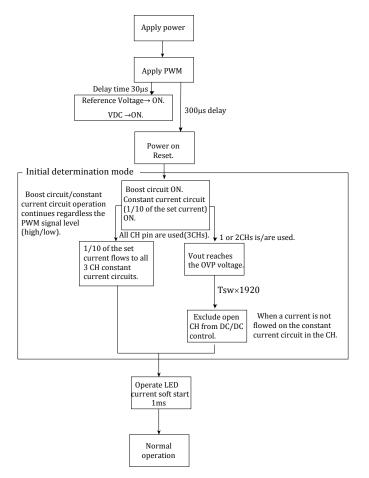


Figure 5. Flowchart at startup

2) Functions

2-1) PWM Input circuit

The AP2152 achieves PWM dimming by applying a PWM signal to the PWM pin. The PWM pin is also used as the enable function of the IC.

At startup, if a high level PWM signal is applied to the PWM pin and maintained for more than 36us, the standby mode will be released. If the high level of PWM signal within the range of 20 M = 20 M = 600 M = 600 M

50Hz \sim 20kHz(F_{PWM} \leq F_{OSC} / 65), is applied longer than 7us to the PWM pin after releasing the standby mode, the operation mode is maintained and direct PWM dimming by PWM signal is simultaneously conducted. The LED current will be the set current configured by the R_{ISET} resistor during a high level of the PWM dimming signal, and the current will be 0mA during a low level of the PWM dimming signal.

If a low level PWM signal is maintained longer than 50ms after the LED is lit, the IC will be in the standby mode.

2-2) 5V Regulator

The AP2152 has a built in low dropout linear regulator to supply voltage for the internal circuits. If a low level is applied to the PWM pin, the VDC is approximately 0V, and if a high level is applied to the PWM pin, the VDC outputs 5V. The VDC pin, the output of the LDO, outputs 5V while the supply voltage ranges from 6V to 35V. If the supply voltage is less than 6V, the output voltage decreases depending on the supply voltage. If the supply voltage goes below the UVLO voltage, the IC ceases operation. If the supply voltage is between the UVLO voltage and 6V, the IC operates but the characteristics are not guaranteed.

Please connect 1uF capacitor between the VDC pin and GND.

2-3) LED current setting

The AP2152 has 3 channel LED constant current circuits built in. By connecting 10 LEDs in series per channel, a maximum of 30 LEDs can be driven. Maximum LED current per channel is 120mA. The LED current can be set in the range from 10mA to 120mA by connecting an external resistor R_{ISET} between the ISET pin and GND. If the ISET pin is affected by noise, the LED current becomes unstable, so R_{ISET} should be placed as close to the IC as possible. The ISET pin sets the LED current for all channels. (CH1~CH3)

The following shows the approximate expression for the LED current and the R_{ISET} connected to the ISET pin. Please check the LED current (thoroughly) when designing the actual board.

ILED(mA) = $\frac{2730}{R_{ISET}(k\Omega)}$

2-4) Switching frequency setting/Synchronize with external clock

The AP2152 can set the DC/DC boost converter switching frequency in the range from 0.2MHz to 2.5MHz by connecting an external resistor RT between the R_T pin and GND. If the RT pin is affected by noise, the switching frequency becomes unstable, so R_T should be placed as closer to the IC as possible.

The AP2152 switching frequency can be synchronized to an external clock signal. If an external clock signal is applied to the SYNC pin, the switching frequency synchronizes to the external clock's rising edge. If a low level is applied to the SYNC pin for approximately 10us during the synchronization operation, it becomes self-oscillating.

(If low level is applied to the SYNC pin in the synchronization operation for approximately 10us, it becomes self-oscillation operation.)

The external clock frequency and the switching frequency set by R_T should be the same. The following shows the approximate expression of the switching frequency and R_T on the RT pin. Please check (thoroughly) when designing the actual board.

$$F_{OSC}(MHz) = \frac{10^3}{7.695 \times R_T(k\Omega) + 80}$$

2-5) Over voltage protection (OVP)/OVP pin short protection

In order not to exceed the internal MOSFET breakdown voltage, the AP2152 has built in over voltage protection. The OVP pin monitors the LED anode voltage divided by the resistor divider. If the OVP pin voltage exceeds 1.20V, the IC ceases boost operation. The LED constant current source maintains operation. If the OVP pin voltage becomes less than 1.20V, the boost operation is resumed. The over current protection function prevents damage by suppressing an overvoltage condition (excessive LED anode voltage) when the load is reduced. This can occur when there is an open condition across one of the LED lines or when the supply voltage fluctuates rapidly.

OVP Voltage = $(1 + \frac{R_{ovp2}}{R_{ovp1}}) \times OVP$ Reference Voltage

OVP reference voltage 1.2V (typ)

The OVP set voltage should be set more than the total voltage of the maximum forward voltage of the LED line plus the error amplifier reference voltage to correctly detect an LED open condition. However the total voltage needs to be less than the Nch power MOSFET maximum rating voltage. The OVP pin short protection is built in. It is activated when the OVP pin voltage becomes less than 0.1V, which is caused by an open across the external Schottkey diode. If the OVP pin short protection is activated, the boost DC/DC convertor operation and the LED constant current circuit ceases, the internal FET for PGOOD is turned on.

2-6) Timer Latch (TM pin) setting

The AP2152 has a built in timer latch type protection circuit. The latch time for the protection circuit is set by connecting an external capacitor C_{TM} between the TM pin and GND. When channel short protection, over current protection, OVP pin short protection, or thermal protection is activated, C_{TM} which is connected to the TM pin is charged by a 10uA constant current. However, the TM pin becomes Hi-Z (high impedance) while PWM = low and the TM pin voltage is maintained.

When the protection circuits continue their operation, the charging of C_{TM} also continues. If the TM pin voltage reaches 2.0V, the DC/DC boost convertor and the LED constant current circuits are latched off and the internal FET for PGOOD is turned on.

In order to restart the IC after it has been turned off by the timer latch function, a low level for more than 50ms needs to be maintained on the PWM pin or the supply voltage needs to be pulled down below the UVLO voltage.

The following shows the approximate expression of the timer latch time and C_{TM} connected on the TM pin. Please check (thoroughly) when designing the actual board. Timer latch time T_{TM} (ms) = 200 × C_{TM} (µF)

2-7) Thermal protection

The AP2152 has a built in thermal protection circuit. If the IC goes into and maintains a high temperature state, the IC will be latched off, therefore the IC needs to be operating below the thermal protection circuit minimum (activation) temperature of 125°C.

2-8) LED open protection

The AP2152 can be operated with one, two or three channels connected. There is not a problem if a CH pin is left open.

For this operation, the AP2152 has a built in LED open detection circuit. If an open CH pin is detected, the CH pin becomes a high impedance and is excluded from the control circuit of the DC/DC boost converter.

If all three CH pins are open, the DC/DC boost converter and the LED constant current circuits are completely turned off. If a capacitor is connected in parallel with the LED line and the LED line is opened, the open detection circuit may not work correctly.

2-9) LED short protection and Cout setting

The AP2152 has a built in LED short protection circuit. If an LED is broken as a short state and the CH pin voltage exceeds 10.8V, the corresponding constant current circuit will be ceased.

If there is an unused CH pin, the LED anode voltage increases up to the OVP setting voltage by the LED open detection circuit. In this case, the CH pin temporarily increases and becomes the same state as the LED short protection, in order to distinguish this case from LED short protection operation, the opened CH pin is excluded using the IC internal counter. For this operation, the Cout value is constrained, so Cout should be determined using the following formula.

LED short protection count time > CH pin voltage rising time (10.8V or higher)

①LED short protection count time = $\frac{1}{Fsw} \times 1920$ ② CH pin voltage rising time = $\frac{Cout \times (Vovp(max) - LEDVf(min) - 10.8V)}{lout \times 0.95}$

2-10) PGOOD function

The PGOOD pin is an Nch open drain output. The internal FET on the PGOOD pin stays off when the supply voltage is 0V (If the PGOOD pin is connected to a pull-up resistor, the PGOOD pin becomes high level) If the supply voltage reaches to approximately 2V, the internal circuits are biased and the internal PGOOD FET turns on. If the supply voltage is more than UVLO and the PWM pin is high, the standby circuit will be released, the IC recognizes as normal operation and the internal PGOOD FET turns off. If a protection circuit is activated after normal operation, the internal PGOOD turns on. (Relationship between protection function and the PGOOD pin state is later described in "Protection Function"). By applying a PWM low level for longer than 50ms, the IC will be reset and the internal PGOOD FET turns on in a standby state.

When the LED anode is shorted to GND, the internal PGOOD FET immediately is turned on by the OVP pin short circuit protection and the PGOOD signal can be used to cut the path from VIN to the LED anode. (Refer to Figure 7)

The AP2152 employs a timer latch method for protection functions. If the FET over current protection, thermal protection, CH short protection, LED open protection, or LED short protection is activated, the IC is latched off and turns off the LEDs.

For example, when the PGOOD pin is monitored by a microcomputer and an abnormal state (PGOOD pin with pull-up resistor is low level) is detected, the microcomputer controls a restart sequence after the IC is reset, so a highly stable system configuration is possible.

Internal Nch FET on PGOOD pin operation

- •Turn off during normal operation
- •Turn on when abnormal operation
- Timer latch off (Over current, CH short, Thermal protection), all CH are open or short, UVLO

•Turn on when in standby state while supply voltage (VIN) is applied. Turn off when VIN is less than 2V

•Turn on without delay by timer circuit when OVP pin short is detected.

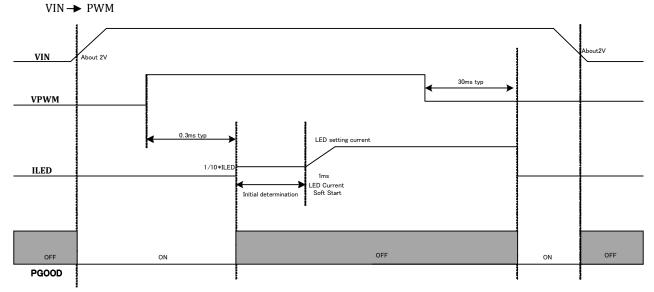


Figure6. PGOOD pin operation

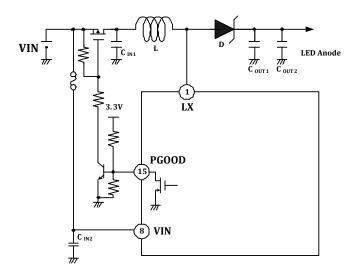


Figure 7. Cut off VIN-LED anode path by using an external FET (example)

2-11) Serial interface

The AP2152 has a built in read only serial interface. By inputting a CLK signal to the SCLK pin, data can be read from the SDATA pin synchronizing with the CLK rising edge. The SDATA pin is an Nch open drain output. The pin needs to be pulled-up to the external power supply.

| | | SDATA | State |
|---|-----|-------|---|
| C | CH1 | Low | LED OPEN or SHORT \Rightarrow CH1 shutoff |
| C | CH2 | Low | LED OPEN or SHORT \Rightarrow CH2 shutoff |
| C | CH3 | Low | LED OPEN or SHORT \Rightarrow CH2 shutoff |
| r | ГМ | Low | Shut-off state by timer latch |

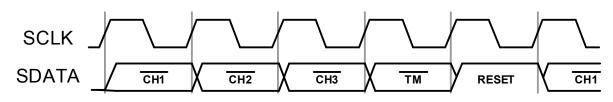


Figure8. Serial Interface Timing Chart

3) Protection Function

| Protection | Description | Detection time Shut-off state | Detection condition | Release condition | PGOOD |
|--------------------------|--|---|--|------------------------------|-----------|
| Thermal | When the IC temperature rises and reaches the detection condition and exceeds the detection time, the DC/DC boost converter and the LED constant current circuit are latched off. | T™ *2 Latch off | 125°Cmin | *1 | ON |
| Over current | Internal Nch power MOSFET drain current is monitored by using an internal detection resistor. If exceeding the detection condition, the power MOSFET is turned off. And if exceeding the detection time, the DC/DC boost converter and the LED constant current circuit are latched off. | Т™ *2 Latch off | 2.6A | *1 | ON |
| Over voltage (OVP) | If the OVP pin voltage reaches the detection condition, the DC/DC boost converter is immediately shut off. In this case, the LED constant current circuit is still operating | LED anode voltage control Auto-release | More than 1.2V | 1.2V or less | OFF |
| OVP pin short | If the OVP pin reaches the detection condition caused by the OVP pin shorted to GND, the LED anode shorted to GND or the Schottky diode open, the DC/DC boost converter and the LED constant current circuit are immediately shut off and the internal PGOOD FET is turned on. If the OVP pin voltage reaches the release condition, normal operation is resumed. If exceeding the detection time, the DC/DC boost converter and the LED constant current circuit are latched off. | Cease all Auto-release ↓ T™ *2 Latch off | Lass than 0.1V | More than 0.1V ↓ *1 | ON |
| UVLO | To prevent malfunction of the IC when the VIN voltage reaches the detection condition. Circuits excluding the UVLO circuit stop the operation. If the VIN voltage returns to the release condition, the IC resumes normal operation. | Cease all Auto-release | 3.75Vmin | 4.45Vmax | ON |
| LDO short | To prevent malfunction and over heating of the IC when the VDC pin shorts to GND. The LDO current is limited to low levels. If the short state goes away, the IC resumes normal operation. | Cease all Auto-release | More than 30mA | 30mA or less | OFF |
| CH short | When the CH pin shorts to GND, the voltage reaches the detection condition, and exceeds the detection time, the DC/DC boost converter and the LED constant current are ceased. | T™ *2 Latch off | 0.1V | *1 | ON |
| LED open | If the CH pin is opened due to an LED disconnection or destruction as an open state, the CH pin is latched off. | Internal timer each CH Latch off | Less than LED set current when OVP Voltage | *1 | OFF *3 |
| LED short | If the CH pin voltage reaches the detection condition due to destruction by an LED short, the CH pin is latched off. | Internal timer each CH Latch off | 12V | *1 | OFF *4 |
| ISET short | To prevent heat generation due to increases in the LED current when the ISET pin shorts to GND, the Nch power MOSFET operation is ceased. If the short state goes away, the IC resumes the normal operation. | Cease Nch Power MOSFET Auto-release | ISET pin GND short | ISET pin normal 1V | OFF |
| RT short | To prevent heat generation due to increases in the switching frequency when the RT pin shorts to GND, the Nch power MOSFET operation is ceased. If the short state goes away, the IC resumes the normal operation. | Cease Nch Power MOSFET Auto-release | RT pin GND short | RT pin Normal 1V | OFF |

Note:

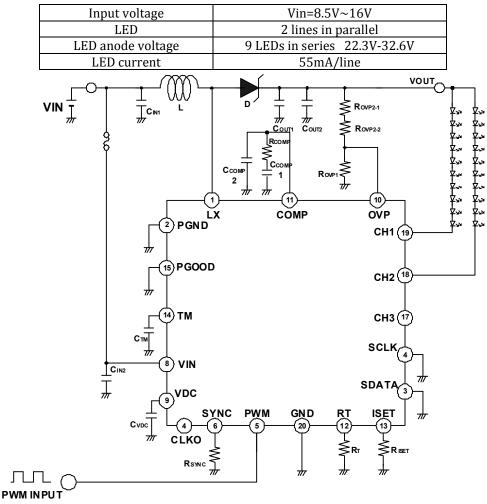
*1. In order to release the latch off state, the PWM pin should be maintained at a low level for 50ms or longer or the supply voltage should be pulled down less than the UVLO voltage.

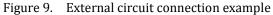
*2. Set time by external capacitor on the TM pin. Refer to the timer latch setting.

*3. OFF when 1 CH or 2 CHs out of 3 CHs is/are open state, ON when all 3 CHs are open state.

*4. OFF when 1 CH or 2 CHs out of 3 CHs is/are short state, ON when all 3 CHs are short state.

APPLICATION (example)



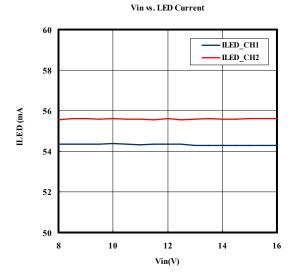


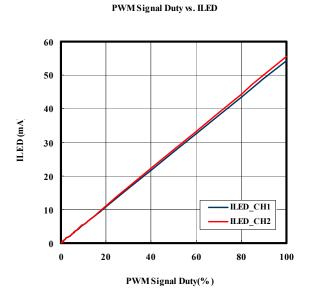
A recommended BOM

| | Symbol | P/N | Value | Maker | Note |
|-----------|---------------------|----------------|------------------------|---------|----------------------|
| | R _T | - | $55k\Omega \pm 0.5\%$ | - | SW frequency 2MHz |
| | R _{ovp1} | - | $30k\Omega \pm 0.5\%$ | - | OVP voltage 37.2V |
| | R _{ovp2-1} | - | $430k\Omega \pm 0.5\%$ | - | OVP voltage 37.2V |
| Resistor | R _{OVP2-2} | - | $470k\Omega \pm 0.5\%$ | - | OVP voltage 37.2V |
| | R ISET | - | 49.7kΩ ±0.5% | - | LED current 55mA |
| | R _{COMP} | - | 1kΩ ±1% | - | Phase compensation |
| | R _{SYNC} | short | 0Ω | - | Self resonant freq. |
| | C _{IN1} | GRM31CR71H475K | 4.7uF/50V | MURATA | Input capacitor |
| | C _{IN2} | CM21X5R105M50A | 1.0uF/50V | KYOCERA | Capacitor for the IC |
| | C _{VDC} | CM05X5R105M06A | 1.0uF/6.3V | KYOCERA | For VDC stability |
| Capacitor | Стм | CM05X5R104M10A | 0.1uF/10V | KYOCERA | Timer latch setting |
| | C _{COMP1} | CM05X5R473M16A | 0.047uF/16V | KYOCERA | Phase compensation |
| | C _{COMP2} | open | - | - | - |
| | Cout1, 2 | GRM31CR71H225K | 2.2uF/50V | MURATA | Output capacitor |
| Diode | D | - | 60V, Io=1A | - | - |
| Inductor | L | #A921CY-150M | D63LCB 15uH | ТОКО | - |

Values in this table are for reference only.

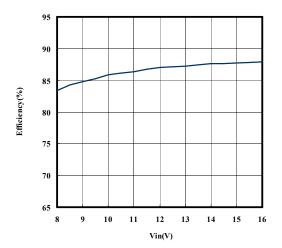
LED current vs. PWM Duty VIN=12V、PWM 200Hz



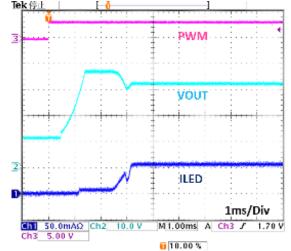


Efficiency vs. Supply voltage

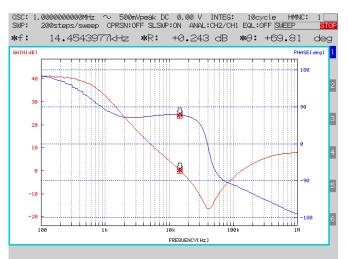




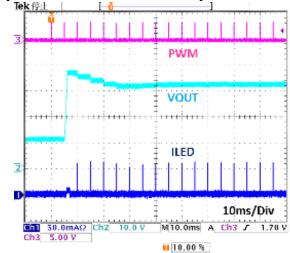
Start-up wave form VIN=12V PWM Duty 100%



Phase margin VIN=12V

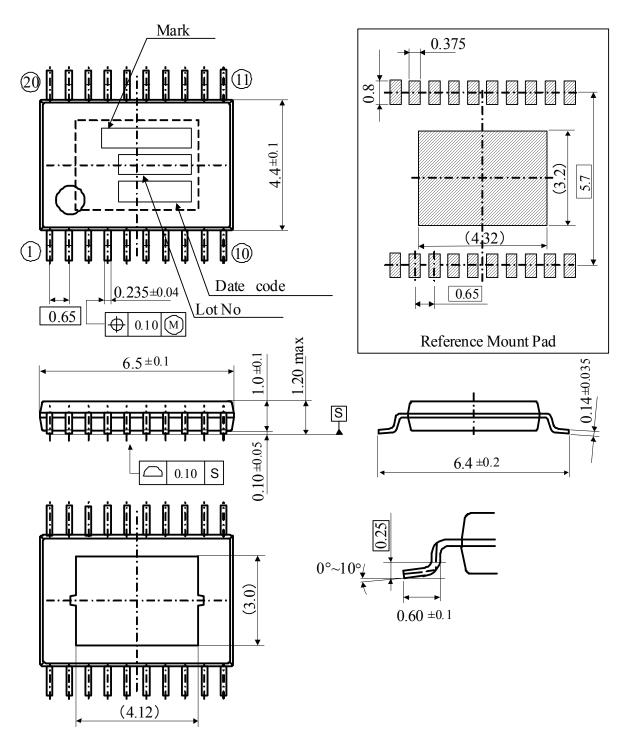


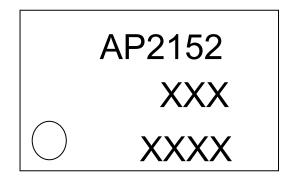
Start-up wave form VIN=12V PWM Duty 0.8% 200Hz



PACKAGE and MARKING

1) Dimension (20 pin HTSSOP)





| Upper | Product name: AP2152 |
|--------|---|
| Center | Assembly lot number: 3 digits |
| Lower | Date code: 4 digits 1 digit (last digit of year) + 2 digits (weekly code) + 1 digit (lot number) |

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